



Feser H-Bridge CPU / GPU / NB / MOSFET Thermal Compound - 5g

Special Price
\$2.40 was
\$11.99

Product Images



Short Description

The Feser Company (TFC) is one of the specialists among the manufacturers of water cooling and is expanding its offerings in this area. In the wake of this development is a separate thermal compound in the name of H-Bridge. The layer between the cooler and the heat source should never be forgotten. Both surfaces look flat, but microscopic valleys are always present and thus never 100% contact is impossible to achieve. A thermal compound fills gaps and allows a transfer of heat over the entire surface.

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With a thermal conductivity of 9.24 W / m ° C is a remarkable performer. The thermal paste is suitable for all types of coolers

suitable: CPU, GPU, Chipset, voltage transformers, etc. The compound is suitable over a temperature range of -30 to +200 ° C guaranteed. With 5g, the amount per tube is plenty for many applications.

Note: This Item can not be shipped using DHL

Specifications

Thermal Conductivity:	3.8 W/m-K
Thermal Impedence:	0.087 U2/W
Specific Gravity:	2.5
Dielectric Constant A (100Hz):	5.1
Viscosity:	No Flowing
Thixotropic Index:	380±10 / 10mm
Operation Temp:	-50~240
Silicone Compounds:	50%
Carbon Compounds:	20%
Metal Oxide Compounds:	30%
Content Syringe:	5g

Additional Information

Brand	The Feser Company
SKU	FESER-H-BRIDGE-D
Weight	0.2000
TIM Type	Paste
Special Price	\$2.40

